

Thermalization of radiation-induced carriers in insulators and wide bandgap semiconductors and semiconductor devices (HEMTs)

(GaN, diamond, β -Ga₂O₃, Si, SiC,... for now)

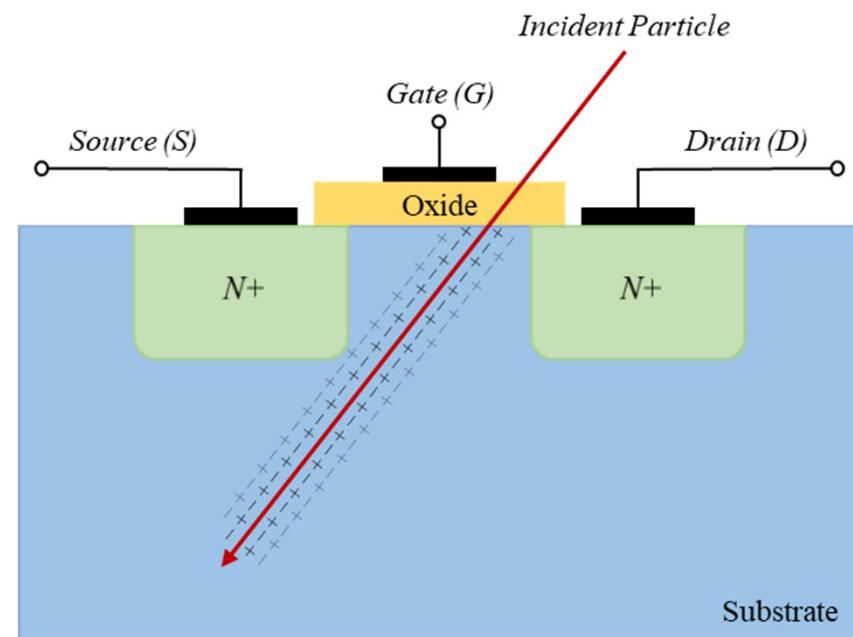
Massimo V. Fischetti and Dallin O. Nielsen
The University of Texas at Dallas, Dept. of Materials Science and Engineering
Emails: max.fischetti@utdallas.edu, dallin.nielsen@utdallas.edu

in collaboration with C. Van de Walle (UCSB),
Laura Nichols, S. Pantelides, R. Schrimpf, and D. Fleetwood (Vanderbilt)

The problem

Simulate single-event effects/upsets (SEE/SEUs) in electron devices

- Basic ingredients
 1. Spatial and energetic distribution of the electron-hole (e-h) pairs after the (proton) strike
 2. Thermalization and diffusion of the e-h pairs
 3. Properties of possible precursor defects at interfaces/bulk (permanent damage)
- Present state of the art to obtain these ingredients
 1. High-energy binary collision Monte Carlo code (*e.g.*, Geant-4, MRED)
 2. Assume instantaneous complete thermalization + drift-diffusion
 3. Empirical cross sections and threshold/activation energies
- Our approach
 1. Use DTF below 100 eV (close the ‘10-100 eV gap’)
 2. Consider e-h pair distributions from step 1 and use full-band Monte Carlo
 3. Cross sections and activation energies also from *ab initio* calculations



Outline

- Review and new results:
 1. Calculated energy-loss function (ELF) from DTF up to 100 eV
Calculated rates for carrier-plasmon, carrier-phonon interactions and impact ionization
 - GaN, β -Ga₂O₃, C (diamond), Si, and SiC (fcc)
 2. Used full-band MC to study carrier relaxation (bulk)
Used distributions after fast relaxation (\sim 100 fs) as initial configuration in Monte Carlo device-simulation code: A GaN/AlGaN HEMT
 - Major coding work on Anduril
 - Test code to calculate hot-electron damage generation in a high-V_{DS}-stressed GaN/AlGaN HEMT (empirical cross section and threshold energy for defect creation)
 - Test code to calculate radiation-induced damage and current transient (upset) during an SEE
 3. Cross sections and activation energies from *ab initio* calculations; with Laura Nichols and Sok Pantelides (VU), and Xiaoguang Zhang (UF) – just starting
 - De-hydrogenation of V_{Ga}-H₃ complexes at the GaN-AlGaN interface of a p-channel HEMT

Summary of new results



1. Thermalization of 100 eV electrons in Si and SiC
2. Damage generated by hot electrons at the GaN-AlGaN interface of a HEMT stressed at high drain bias
3. Damage induced by 100 eV electrons in a GaN/AlGaN HEMT
4. Dehydrogenation of $V_{\text{Ga}}\text{-H}_3$ complexes at the GaN-AlGaN interface

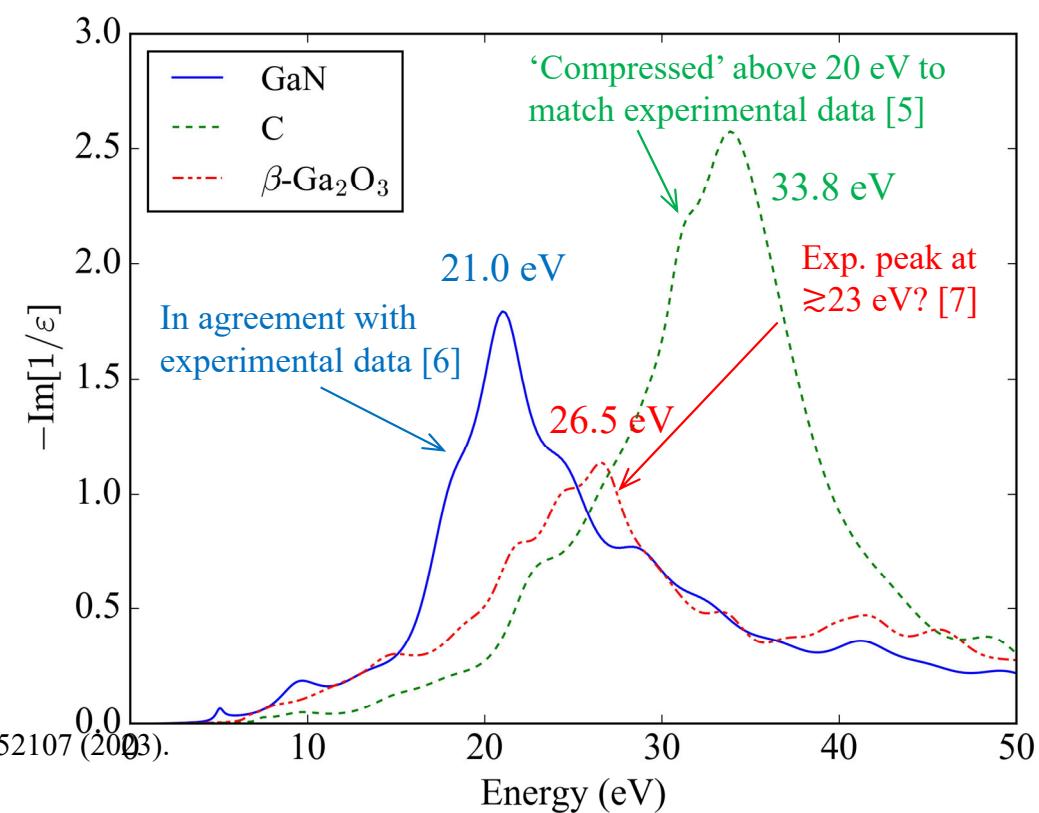
Only “proof-of-concept” (or ‘work in progress) for now.

Missing:

1. GaN hole transport in MC device code
2. Reliable information about defect precursors
3. Pair momentum distribution in the ‘streak’
(... but probably already isotropic in ~100 fs)

First Principles Calculations [1]

- DFT and DFPT (*Quantum ESPRESSO* [2])
 - Band structure
 - “Scissor operator” to fit gap including also excitonic effects when significant (diamond)
 - Phonon dispersion
 - Dielectric function (TDDFT, *turboEELS* [3])
 - Plasmon emission and impact ionization from energy-loss (EL) function $\text{Im} \left(\frac{-1}{\epsilon(\mathbf{q}, \omega)} \right)$
- EPW [4]: Carrier-phonon matrix elements
- Loss function:
 - Stronger peaks → higher plasmon emission rate
 - GaN and β - Ga_2O_3 plasmon energies lower than C → slower carrier thermalization



[1] D. O. Nielsen *et al.*, Phys. Rev. B **108**, 155203 (2023); Appl. Phys. Lett. **123**, 252107 (2023).

[2] P. Giannozzi, *et al.*, J. Phys. Cond. Matt. **21**, 395502 (2009).

[3] I. Timrov, *et al.*, Comput. Phys. Commun. **196**, 460 (2015).

[4] S. Poncé, *et al.*, Comput. Phys. Commun. **209**, 116 (2016).

[5] J. Cañas *et al.*, Appl. Surf. Sci. **461**, 93 (2018).

[6] R. Dhall, *et al.*, Appl. Phys. Lett. **112**, 061102 (2018).

[7] C. Fares *et al.*, ECS J. Solid State Sci. Technol. **8**, Q3154 (2019) (Surface losses from REELS. Data only up to 25 eV).

Scattering Rates: Calculation [1]



- Carrier-phonon scattering (Fermi's Golden Rule, FGR):

$$\frac{1}{\tau_n^{(\eta)}(\mathbf{k})} = \frac{2\pi}{\hbar} \sum_{n'q} |g_{nn'}^{\eta}(\mathbf{k}, \mathbf{q})|^2 \left(N_q + \frac{1}{2} \mp \frac{1}{2} \right) \delta [E_n(\mathbf{k}) - E_{n'}(\mathbf{k} \pm \mathbf{q}) \pm \hbar\omega_q^{(\eta)}]$$

- $N_q = 1/(e^{(\hbar\omega_q/k_B T)} - 1)$ (assuming T=300 K)
- Evaluation of delta function done by Blöchl's tetrahedron method [2].

- Carrier energy-loss rate (ELR)

- Electron energy loss spectroscopy (STM-EELS)
 - Peaks = impact ionization and plasma excitations (see figure)
- Total rate using dielectric function (directly related to EEL cross section), FGR and dissipation fluctuation theorem [3-5]:

$$\frac{1}{\tau_n^{\text{ELR}}(\mathbf{k})} = \frac{2\pi}{\hbar} \sum_{n'} \int \frac{d\mathbf{q}}{(2\pi)^3} \frac{e^2 \hbar}{q^2} \int \frac{d\omega}{2\pi} \text{Im} \left[\frac{-1}{\varepsilon(\mathbf{q}, \omega)} \right] \delta [E_n(\mathbf{k}) - E_{n'}(\mathbf{k} + \mathbf{q}) \pm \hbar\omega].$$

- Assume a low radiation-dose rate: Small density, no conduction-band el-el scattering, no heating

[1] D. O. Nielsen *et al.*, Phys. Rev. B **108**, 155203 (2023); Appl. Phys. Lett. **123**, 252107 (2023)..

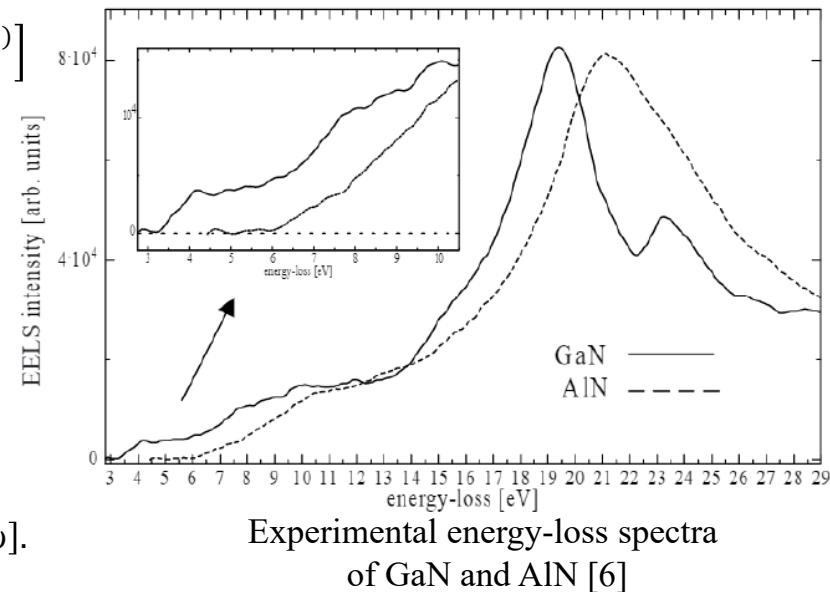
[2] P. E. Blöchl, O. Jepsen, and O. K. Andersen, Phys. Rev. B **49**, 16223 (1994).

[3] P. Nozières and D. Pines, *Theory of Quantum Liquids*, Advanced Book Classics Series (Westview Press, Boulder, CO, 1999).

[4] H. Nyquist, Phys. Rev. **32**, 110 (1928)/

[5] H. B. Callen and T. A. Welton, Phys. Rev. **83**, 34 (1951).

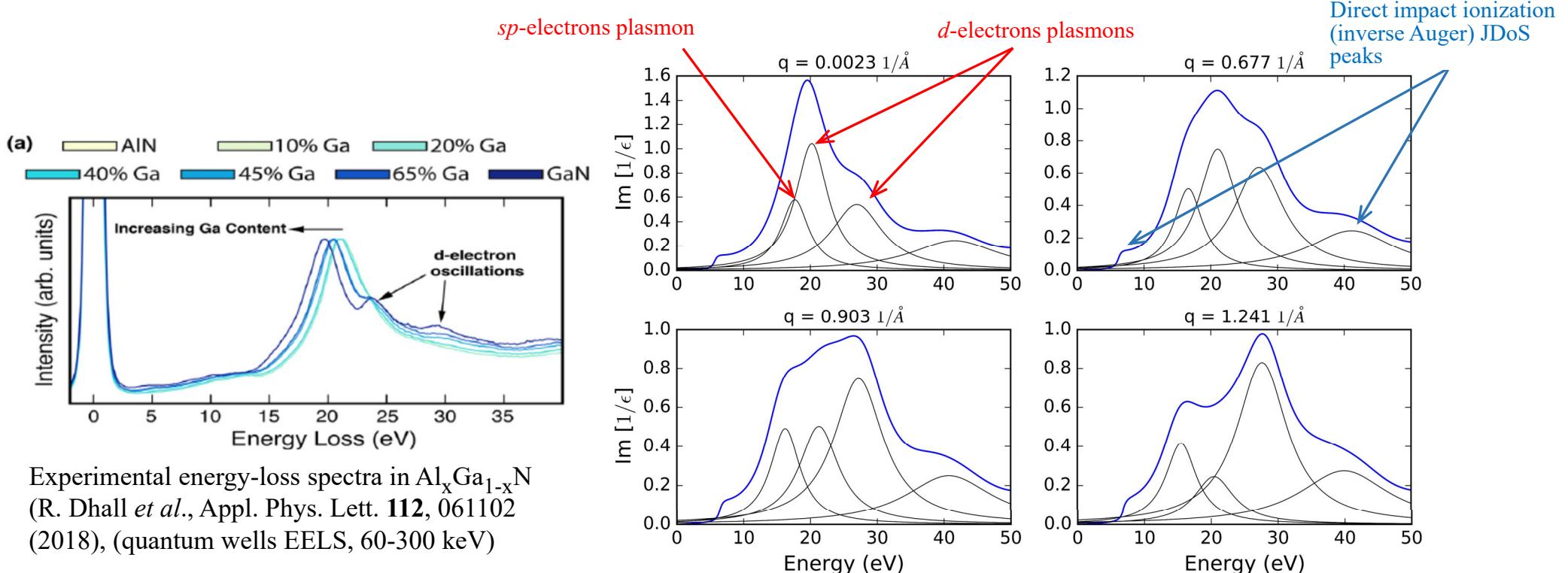
[6] G. Brockt and H. Lakner, Micron **31**, 435 (2000).



The energy-loss function $\text{Im} \left[-\frac{1}{\varepsilon(\mathbf{q}, \omega)} \right](\text{GaN})$



(from the RPA, finding plasmons and JDos peaks via Lorentzian fits... just to understand, but academic*)

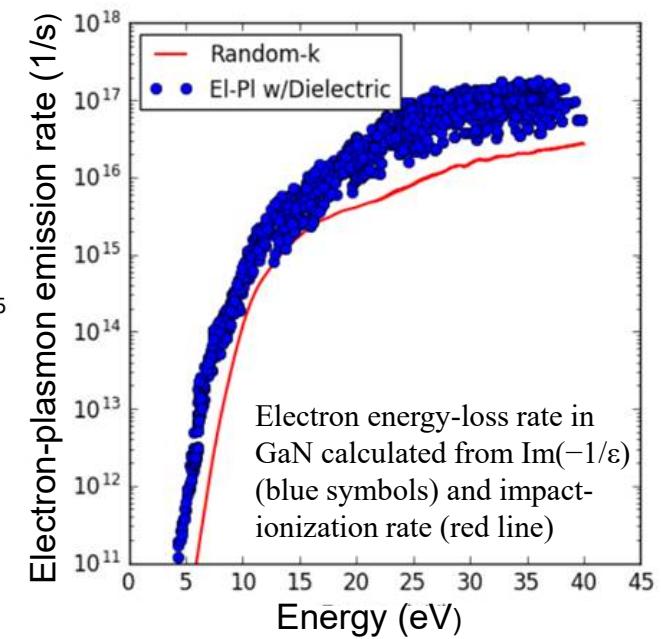
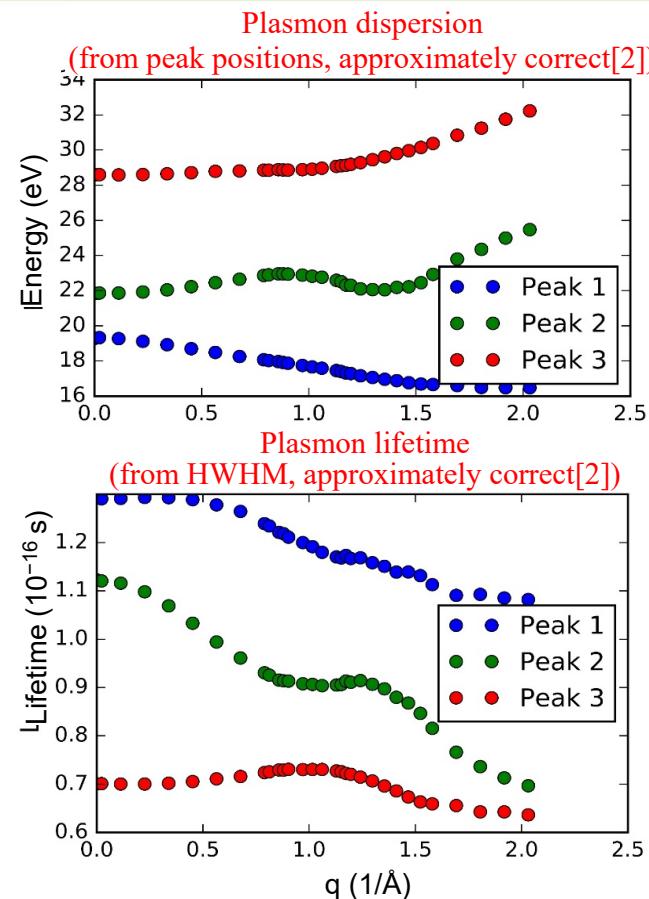
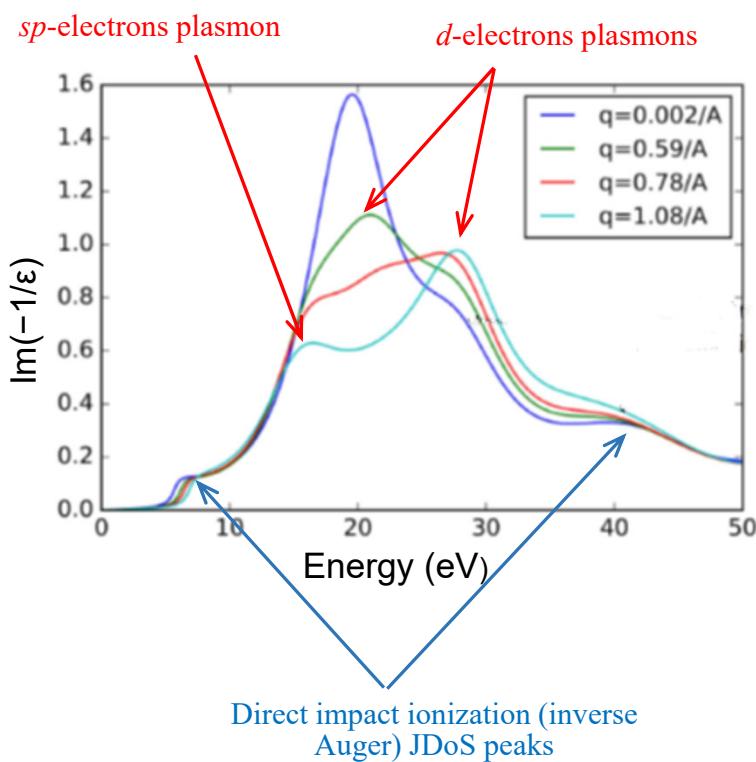


Experimental energy-loss spectra in $\text{Al}_x\text{Ga}_{1-x}\text{N}$
 (R. Dhall *et al.*, Appl. Phys. Lett. **112**, 061102
 (2018), (quantum wells EELS, 60-300 keV)

(*Except for ‘vertex corrections’)

$$\epsilon^{(r)}(\mathbf{q}, \omega) = 1 - \frac{e^2}{q^2 \epsilon_0} \sum_{\mathbf{G}, \mathbf{k}, \mu, \mu'} \frac{[p(\mathbf{k}, \mu) - p(\mathbf{k} + \mathbf{q}, \mu')] |\langle \mathbf{k} + \mathbf{q} + \mathbf{G}, \mu' | e^{i\mathbf{q} \cdot \mathbf{r}} | \mathbf{k}, \mu \rangle|^2}{E_\mu(\mathbf{k}) - E_{\mu'}(\mathbf{k} + \mathbf{q}) + \hbar\omega + i\hbar s}$$

sp- and *d*-electrons plasmon: Dispersion and lifetime (GaN) [1]



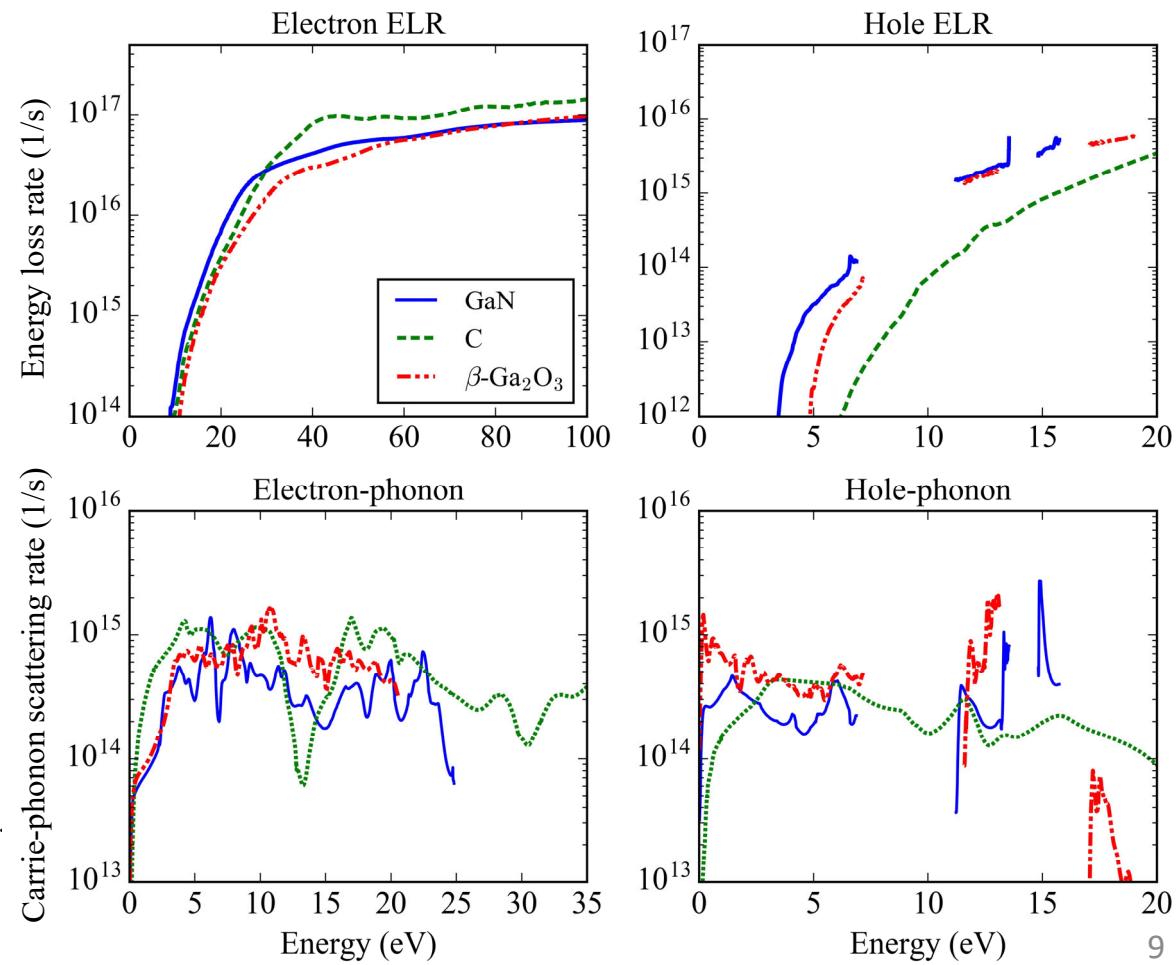
[1] D. O. Nielsen *et al.*, Phys. Rev. B **108**, 155203 (2023).

[2] P. Hamann *et al.*, Contrib. Plasma Phys. **10**, e202000147 (2020)

Scattering/Energy-Loss Rates



- Phonon scattering and ELR
- Electrons:
 - Phonon scattering dominant for low energies ($\lesssim 10\text{-}15$ eV)
 - ELRs flatten as energy increases (reaches $\sim 10^{17}$ 1/s; broadening still acceptable)
 - Quinn, Ferrell, Pines, Penn calculated rates of similar magnitude [2-5]
 - Ga-based materials driven to high magnitudes by dense d bands; diamond by large loss function
- Holes:
 - Phonon scattering dominant for low energies
 - GaN spikes at ~ 13 and 15 eV from d bands



- [1] D. O. Nielsen *et al.*, Phys. Rev. B **108**, 155203 (2023) (GaN only).
- [2] D. Pines, Rev. Mod. Phys. **28**, 184 (1956).
- [3] J. J. Quinn and R. A. Ferrell, Phys. Rev. **112**, 812 (1958).
- [4] J. J. Quinn, Phys. Rev. **126**, 1453 (1962).
- [5] D. R. Penn, Phys. Rev. **35**, 482 (1987).

Hot Electron Thermalization

- Solved semi-classical BTE
 - Full bands [1,2]
 - Zero field, 300 K
 - 1000 electrons ($E \sim 100$ eV)
- Electrons
 - Rapid energy loss ($t < 10^{-16}$ s)
 - Plasmon emission/impact ionization
 - Thermalization rate decreases ($t > 10^{-16}$ s)
 - Phonon scattering to thermal when energy falls below impact-ionization threshold
- Holes
 - Initial hole buildup
 - No rapid initial decrease (no plasma excitations)
 - Steeper slope (larger frame)

[1] H. Shichijo and K. Hess, Phys. Rev. B **23**, 4197 (1981).

[2] M. V. Fischetti and S. E. Laux, Phys. Rev. B **38**, 14 (1988).

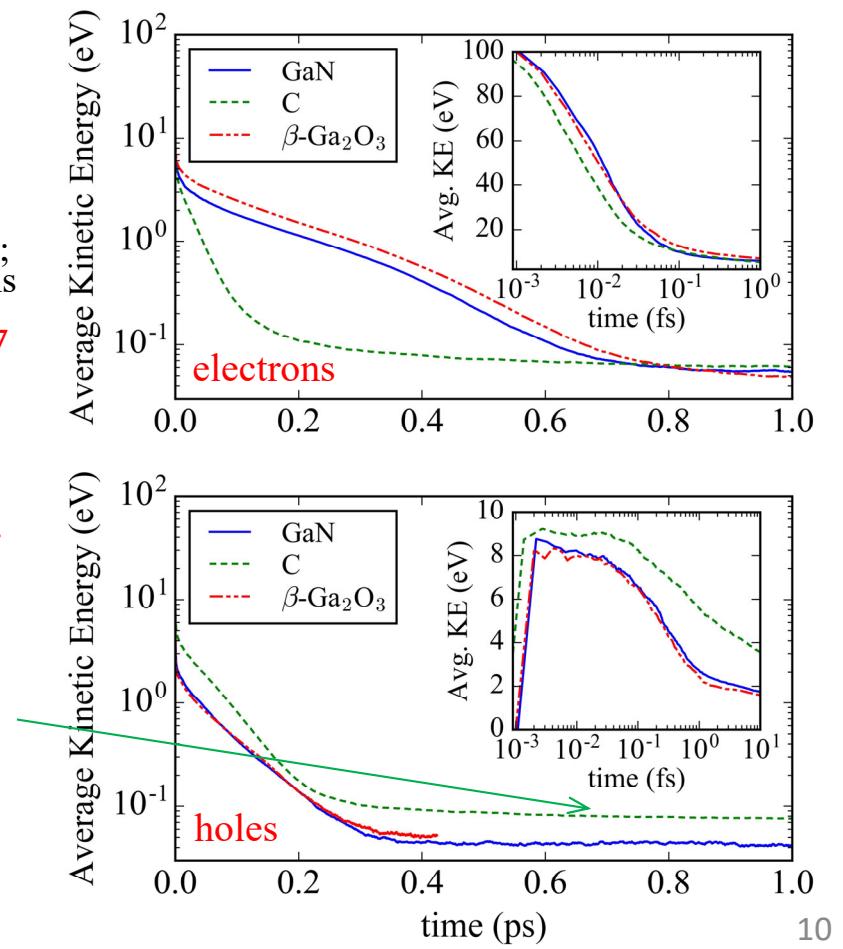
[3] P. J. Sellin and J. Vaitkaias, Nucl. Instrum. Methods Phys. Res. A **557**, 479 (2006).

[4] E. B. Yakimov, *et al.*, Appl. Phys. Lett. **118**, 202106 (2021).

[5] J. W. Keister, *et al.*, J. Synchrotron Rad. **25**, 407 (2018).

- GaN
 - Electrons thermalize in ~ 1 ps; holes in ~ 0.5 ps
 - **Average energy per pair ~ 8.9 eV/pair** [3,4]
- C (diamond)
 - Electrons thermalize in ~ 0.2 ps; holes in ~ 0.3 ps (large plasmons energy)
 - **Average energy per pair ~ 12.87 eV/pair** [5]
- β -Ga₂O₃
 - Electrons thermalize in ~ 1 ps; holes in ~ 0.5 ps
 - **Average energy per pair ~ 11.24 eV/pair** [4]

Slow hole thermalization in C
due to small hole-phonon
scattering rates below ~ 0.5 eV



New results

1. Thermalization of 100 eV electrons in Si and SiC

- Small gap and Lorentzian broadening used by TurboEELs for ELF caused issues. Used “epsilon.x” instead.

2. Damage generated by hot electrons at the GaN-AlGaN interface of a HEMT stressed at high drain bias

- Two defect precursors with small/slow observed V_{th} -shift (~ 10 mV/hour) [1]:

$$N_1^\infty = 1.46 \times 10^{11} \text{ cm}^{-2} \quad \sigma_1 = 8.2 \times 10^{-16} \text{ cm}^2 \quad E_1 = 0.6 \text{ eV}$$

$$N_2^\infty = 3.6 \times 10^{10} \text{ cm}^{-2} \quad \sigma_2 = 2.3 \times 10^{-16} \text{ cm}^2 \quad E_2 = 1.4 \text{ eV}$$

- No GaN holes in Anduril (yet): Possible V_{th} -shift due to floating-body effects; faster/larger predicted V_{th} -shift (6 orders-of-magnitude): Increase E_1, E_2 , decrease σ_1, σ_2

3. Damage induced by 100 eV electrons in a GaN/AlGaN HEMT

- No GaN holes in Anduril (yet): Only qualitative estimates for small density

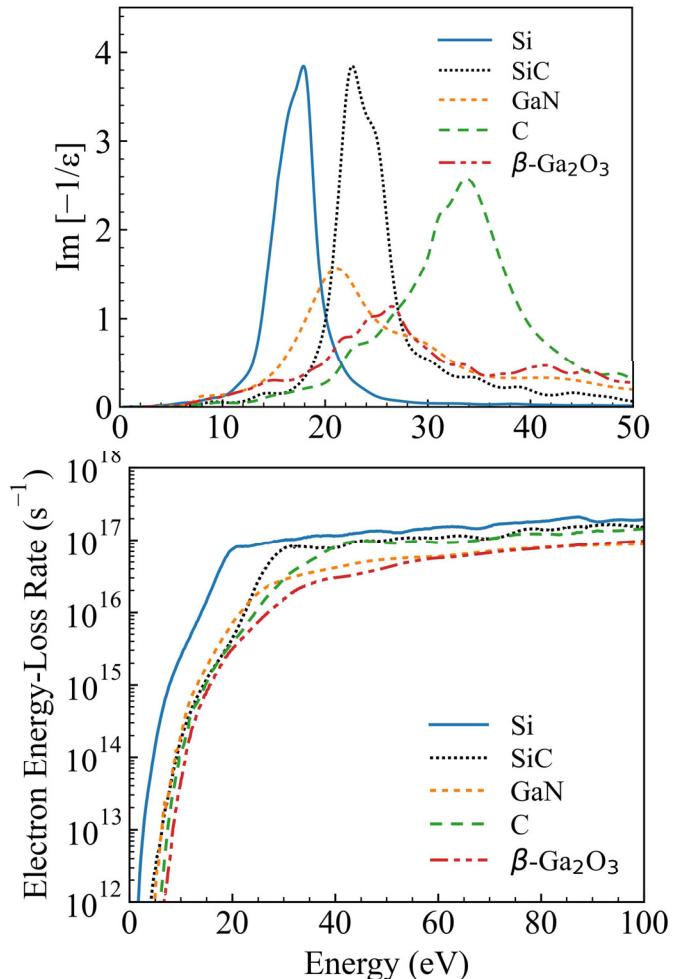
4. Dehydrogenation of V_{Ga} -H₃ complexes at the GaN-AlGaN interface (p-channel HEMT)

- Provided Laura and Sok hot-hole distributions to test their codes

1. Thermalization in Si and SiC



- Loss function of Si
 - Peak near predicted value (el gas: 16.4 eV)
 - Largest peak magnitude
- Loss function of SiC
 - Peak magnitude and area similar to Si
- Energy-loss rates
 - Si: reaches 10^{17} s^{-1} at $\sim 20 \text{ eV}$; SiC: at $\sim 30 \text{ eV}$
 - collisional broadening ($\sim 33 \text{ eV}$)
 - Caused by large loss function (peak magnitude and area)
 - Si: Small gap \rightarrow large DOS for generated pairs
 - SiC: Large hole DOS \rightarrow relatively large JDOS

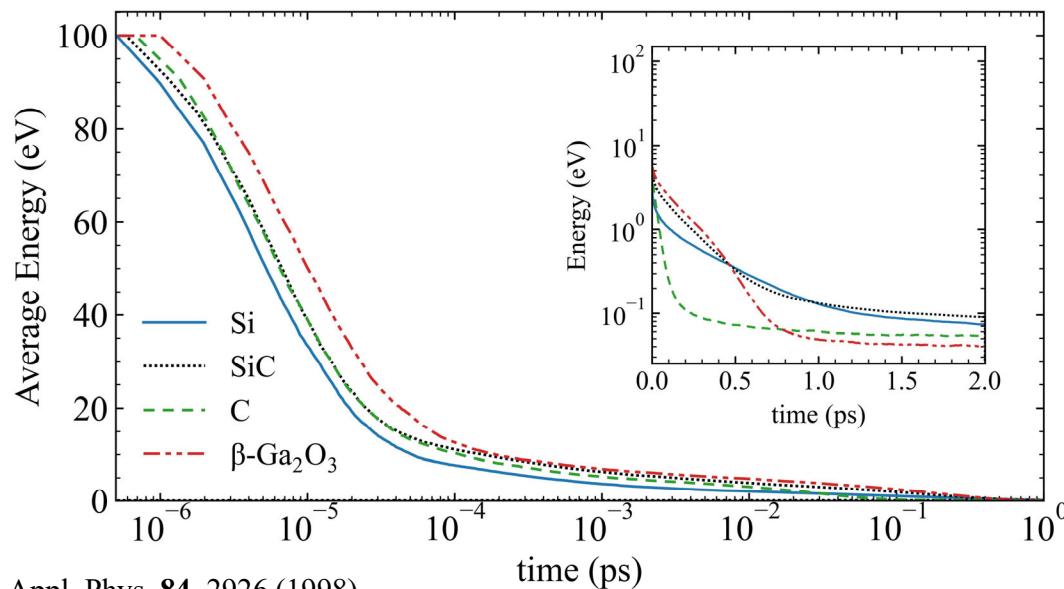


[1] D. O. Nielsen *et al.*, Phys. Rev. B **108**, 155203 (2023) (GaN only).

[2] D. O. Nielsen and M. V. Fischetti, Appl. Phys. Lett. **123**, 252107 (2023) (Ga_2O_3 and C)

1. Thermalization in Si and SiC

- Initially, energy drops fastest in Si → high ELR
 - SiC and C nearly overlap → similar ELR
 - $\beta\text{-Ga}_2\text{O}_3$ lowest ELR (GaN very similar)
- Inset figure:
 - Final stages depend on phonon scattering rates
 - Low phonon scattering rates in Si and SiC cause slow thermalization.
- Pair creation energy:
 - Si: 3.4 eV/pair (Exp: 3.6 eV/pair [1])
 - SiC: 7.2 eV/pair (Klein's expression: 7.21 eV/pair [2])
 - GaN: 8.9 eV/pair
 - $\beta\text{-Ga}_2\text{O}_3$: 11.2 eV/pair
 - C: 12.9 eV/pair



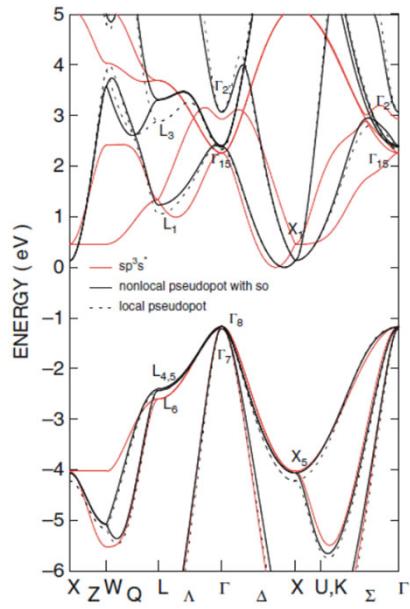
[1] F. Scholze, H. Rabus, and G. Ulm, J. Appl. Phys. **84**, 2926 (1998).

[2] C. A. Klein, J. Appl. Phys. **39**, 2029 (1968).

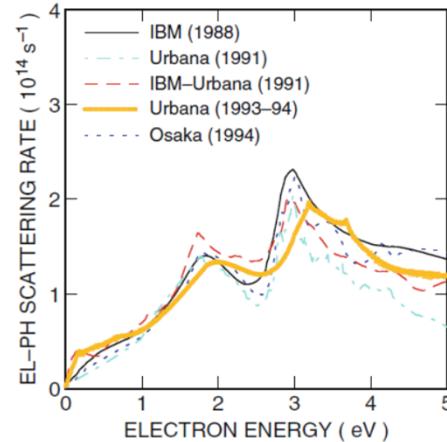
2. The template of much older work: Damage generated at the interface of a Si MOSFET



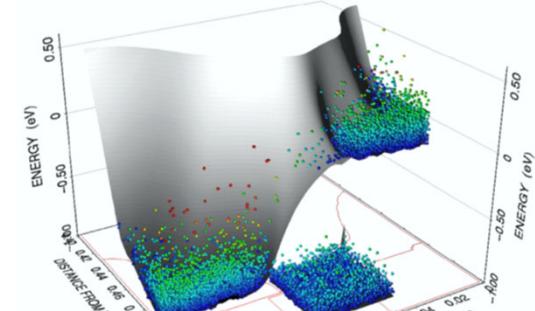
Empirical-pseudopotential/DFT
band structure [1]



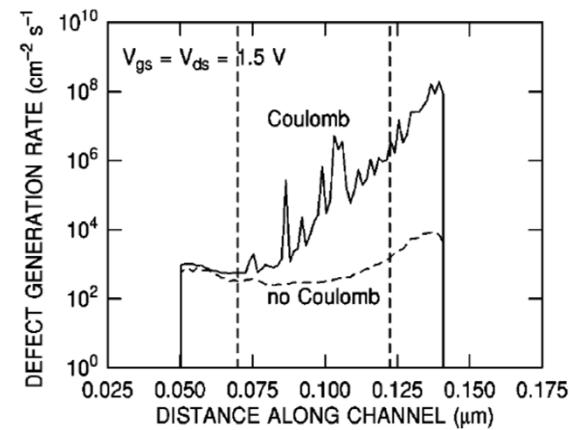
Electron-phonon (and more) scattering rates [1]



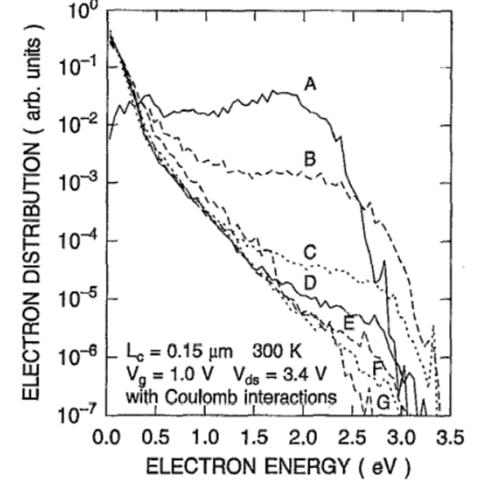
The device



Hot carriers along
the channel [1]



Defects generated at the
Si/SiO₂ interface:
 $P_g = \exp(E/\Delta E)$
(empirical model) [2]

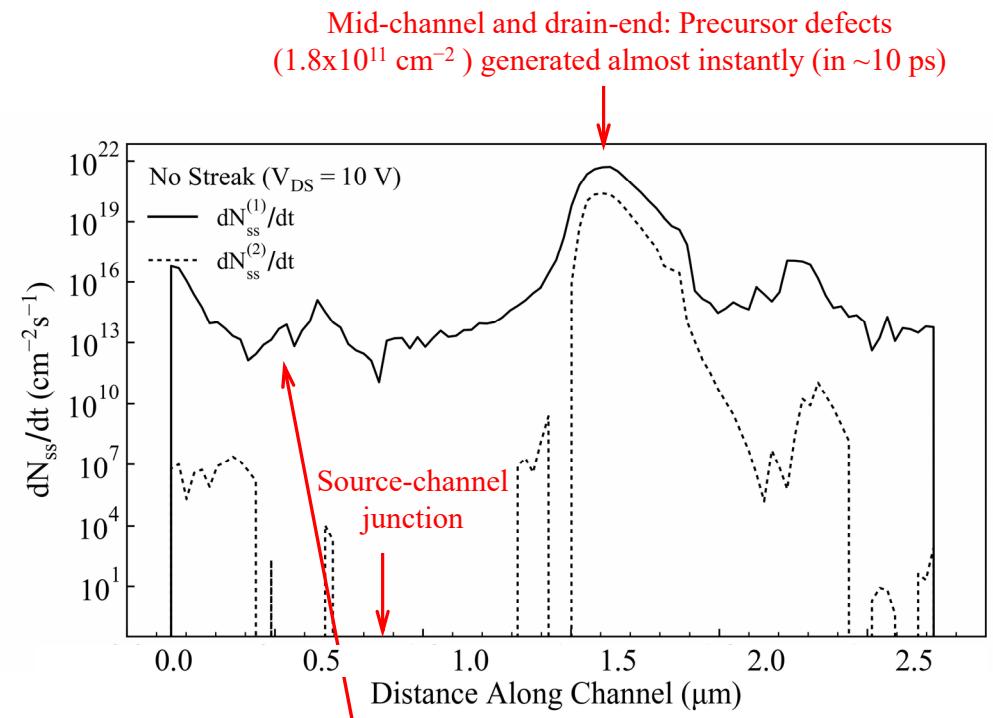
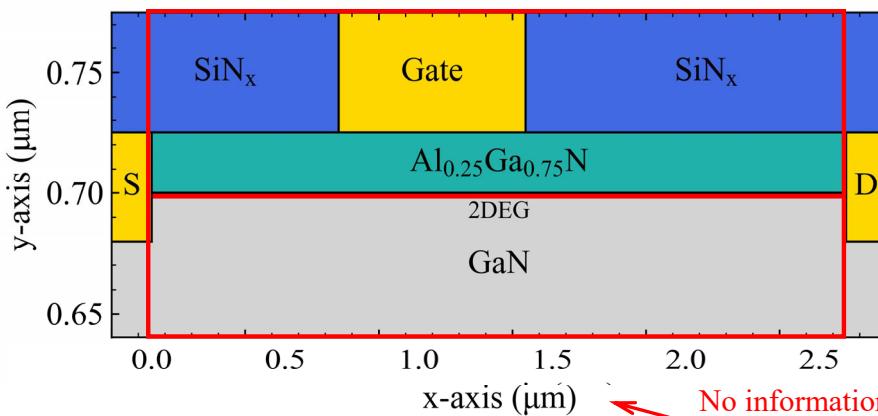


[1] M. V. Fischetti, S. E. Laux, and E. Crabbé, J. Appl. Phys. **78**, 1058 (1995); M. V. Fischetti and S. E. Laux, J. Appl. Phys. **89**, 1205 (2001); [2] D. J. DiMaria, J. Appl. Phys. **87**, 8707 (2000)

2. Damage generated at the GaN-AlGaN interface of a HEMT



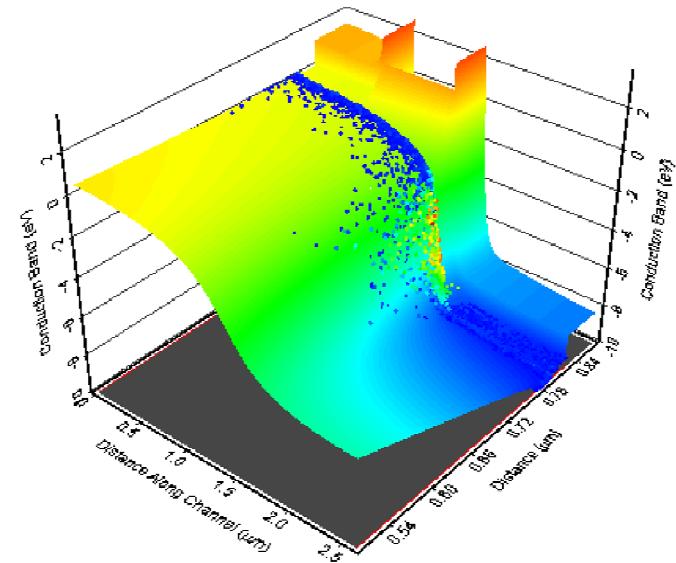
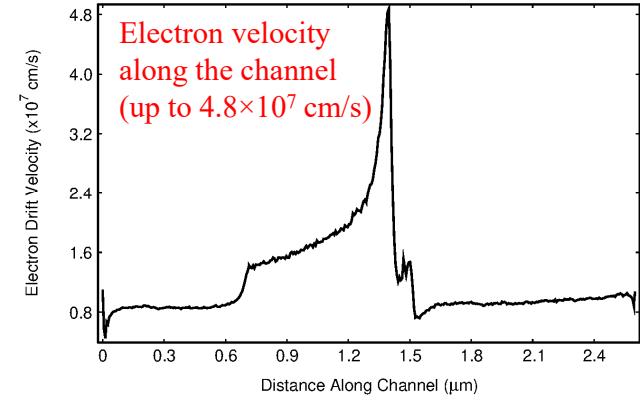
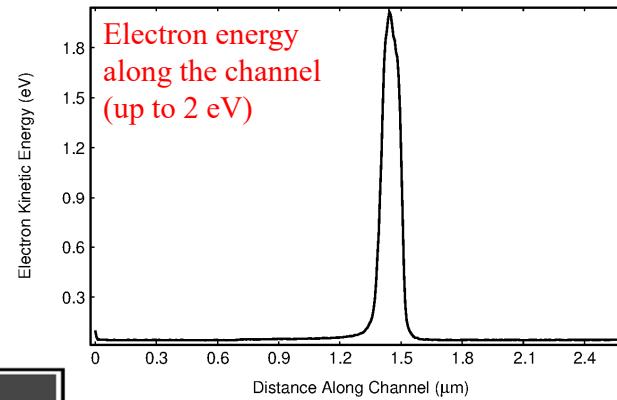
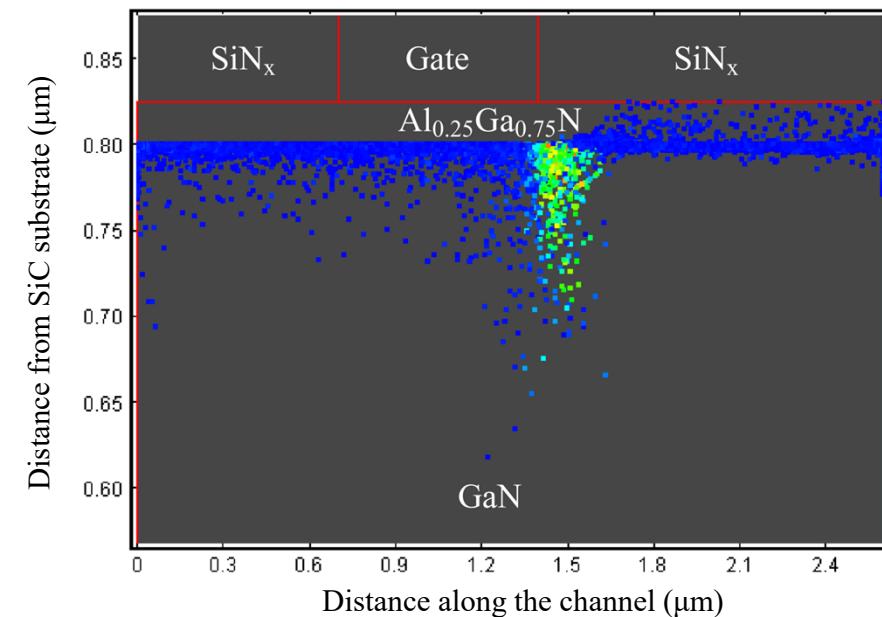
- Hot-electron induced damage at the GaN-AlGaN interface of n-channel HEMTs [1]
- With published parameters (N_∞, σ_i), found very high defect-generation rate near the source, $\sim 10^{13} \text{ cm}^{-2}\text{s}^{-1}$ @ $V_{DS}=10 \text{ V}$; **but:** very slow V_{th} shift ($\sim 10 \text{ mV/hours}$), seen in experiments, $\sim 10^6 \text{ cm}^{-2}\text{s}^{-1}$ @ $V_{DS}=20 \text{ V}$ [1]



2. Damage generated at the GaN-AlGaN interface of a HEMT



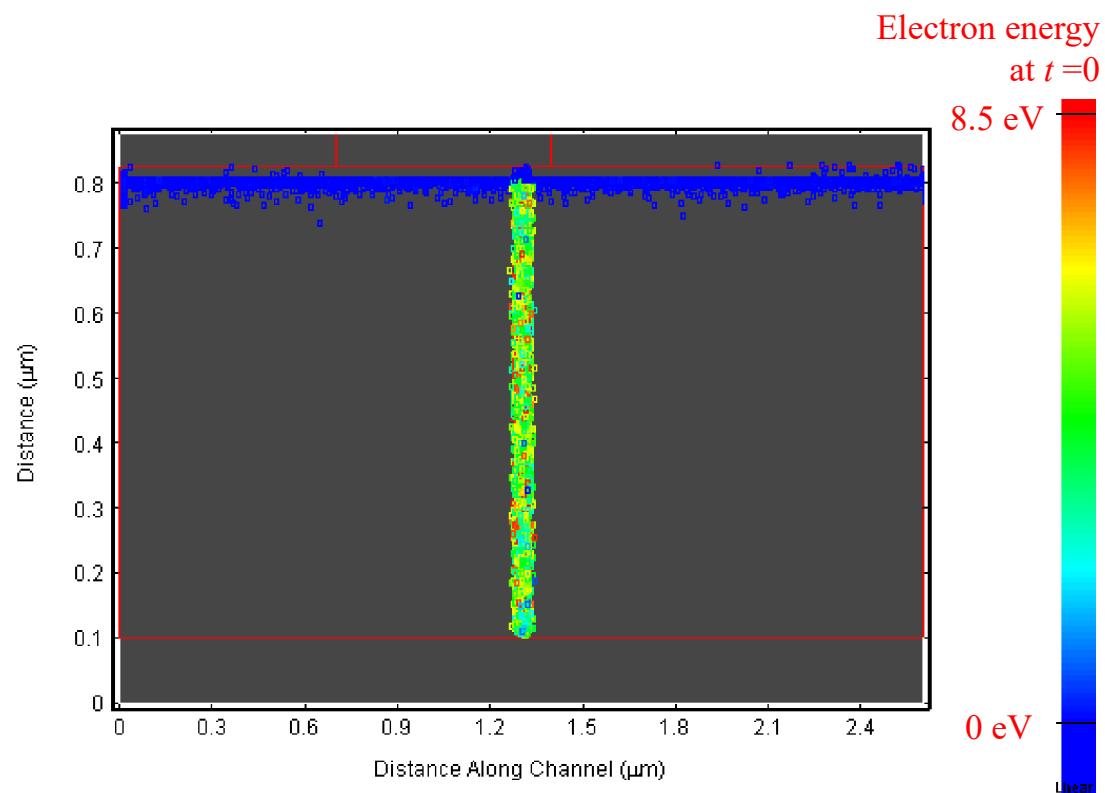
- GaN-AlGaN n-channel HEMT; $V_{DS} = 10$ V, $V_{GS} = 0$ V
- Hot electrons near drain-edge of gate → Large defect generation rate near drain
- Mostly thermal electrons near source → Small defect generation rates



3. Damage induced by 100 eV electrons in a GaN/AlGaN HEMT



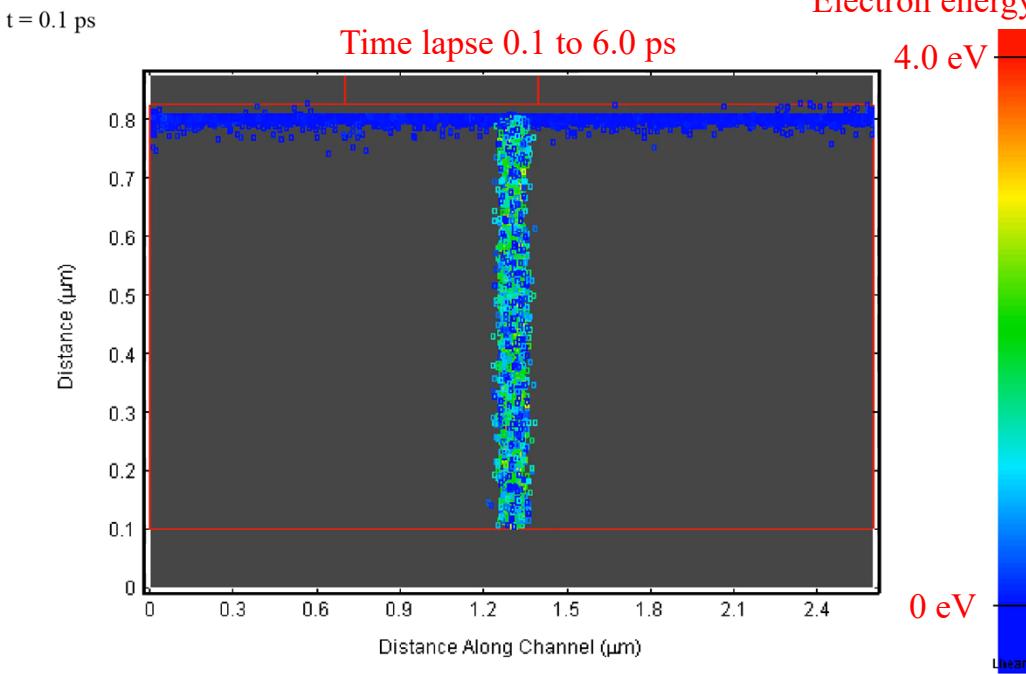
- Mimic with optically-generated pairs ($h\nu = 12.1$ eV) the spatial and energetic pair distribution from 100 eV relaxation after 120 fs:
 - Average electron energy ~ 8.7 eV
 - Gaussian width ~ 20 nm
 - Initial peak density $\sim 10^{18} \text{ cm}^{-3}$,
(expect 10^{21} - 10^{22} cm^{-3} , for a 10 MeV proton [1],
LET ~ 10 - 15 MeV $\text{cm}^2/\text{mg} \sim 6 \times 10^{10} \text{ eV/cm}$)
- Calculate generation rate of defects at the GaN-AlGaN interface of an n-channel HEMT at $V_{DS} = 1$ V



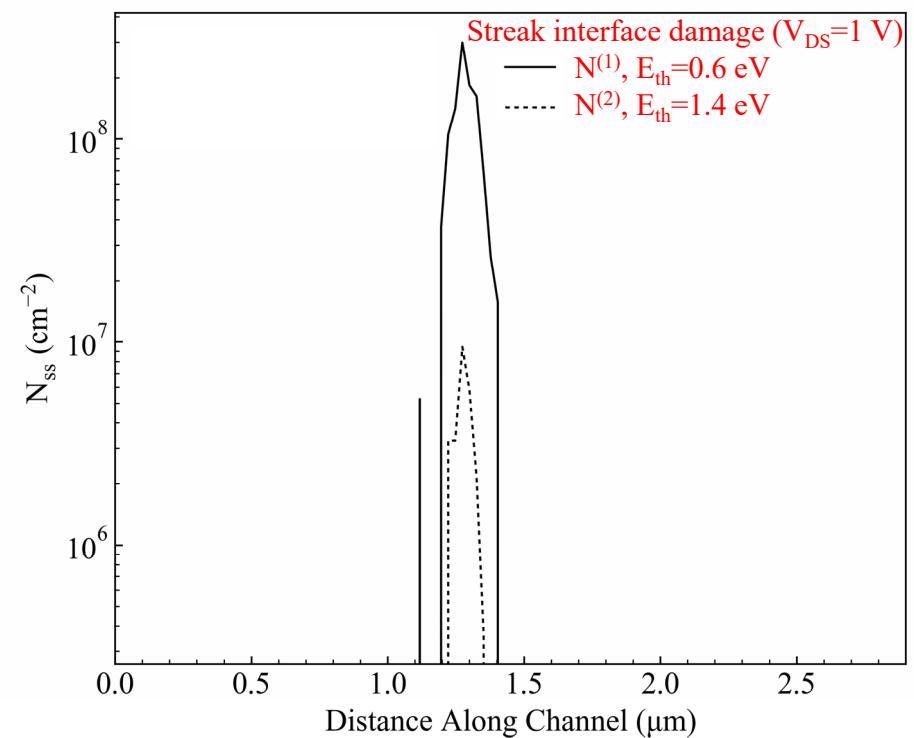
[1] J. Osheroff *et al.*, IEEE Trans. Nucl. Sci. **68**, 597 (2012).

3. Damage induced by 100 eV electrons in a GaN/AlGaN HEMT

- Low V_{DS} (1 V) prevents damage from energetic electrons in channel
- Damage from streak confined to relatively narrow region (~ 300 nm); induced at early times (< 1 ns)



Peak ‘streak’ density 10^{18} cm^{-2} , Gaussian width ~ 20 nm



Issues:

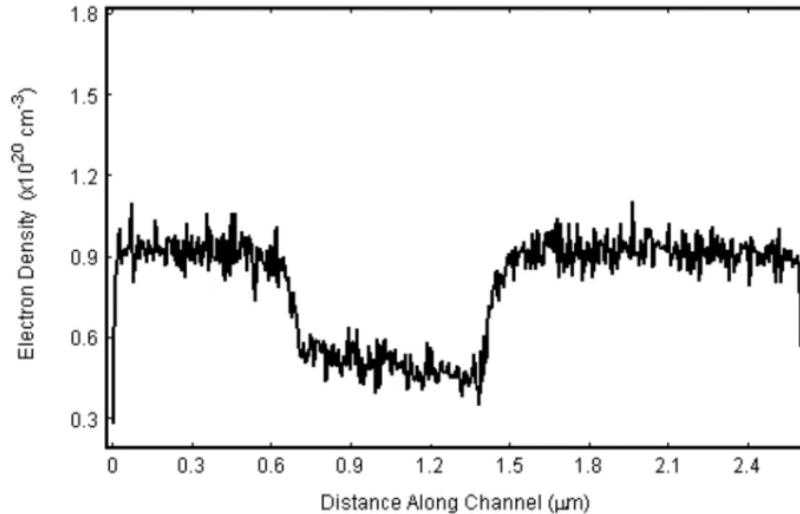
1. Frozen field (no holes)
2. Zero total momentum (need info from Geant4)
... but likely already isotropic in ~ 100 fs)

3. Damage induced by 100 eV electrons in a GaN/AlGaN HEMT



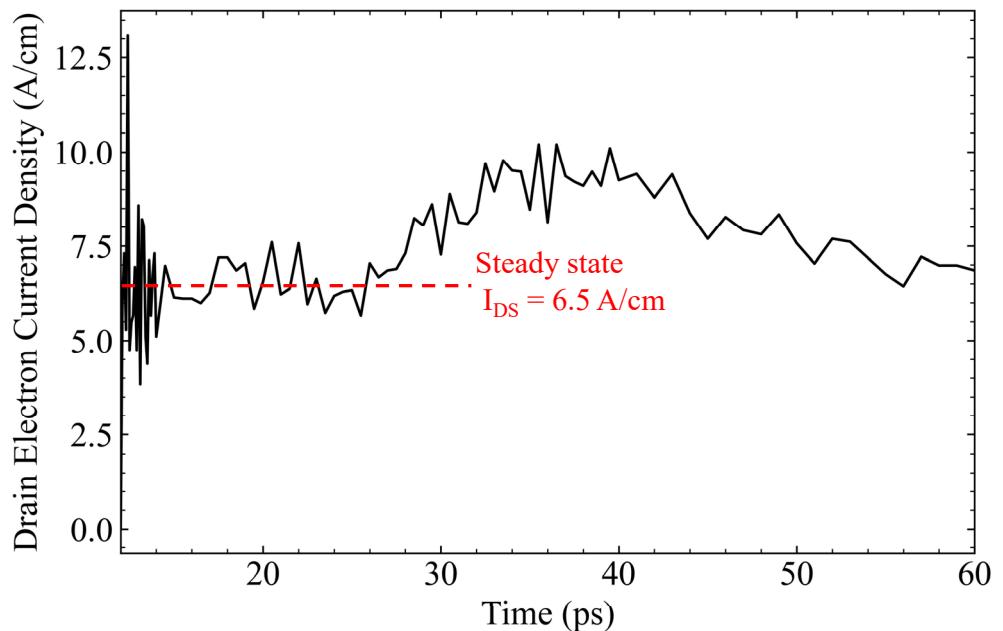
- Track radiation-induced excess charge and current at the contacts
- Video: Carrier density in channel as function of time
 - “Wave” of electrons builds near streak location
 - Moves toward drain contact and disappears after ~ 40 ps
- This behavior is reflected in plot of current vs. time
 - Initially, current density remains near pre-streak levels
 - Apparent increase in current at about 25 ps signifies arrival of “wave”

Electron density along channel
Time lapse 0 to 60 ps



time = 12.000 ps; data range is $2.83e+19 \rightarrow 1.11e+20 (\text{cm}^{-3})$ #

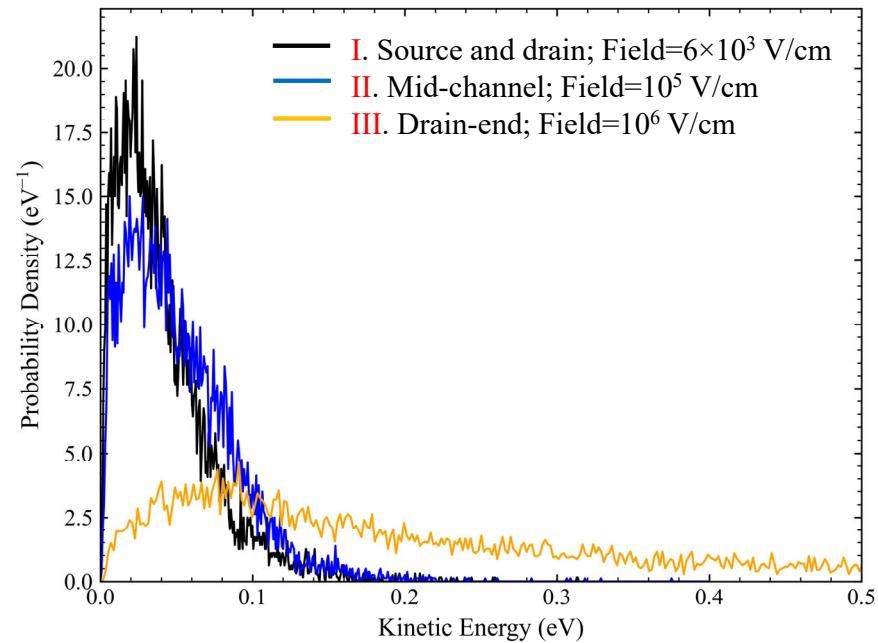
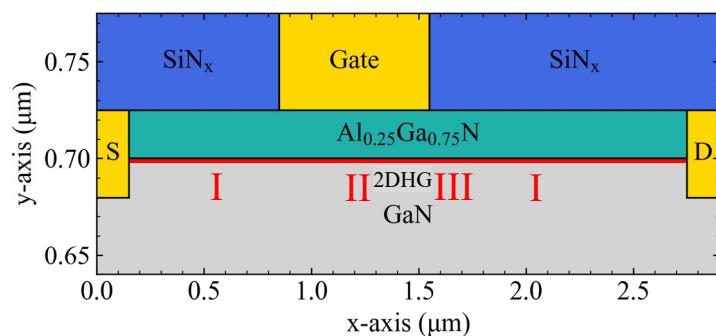
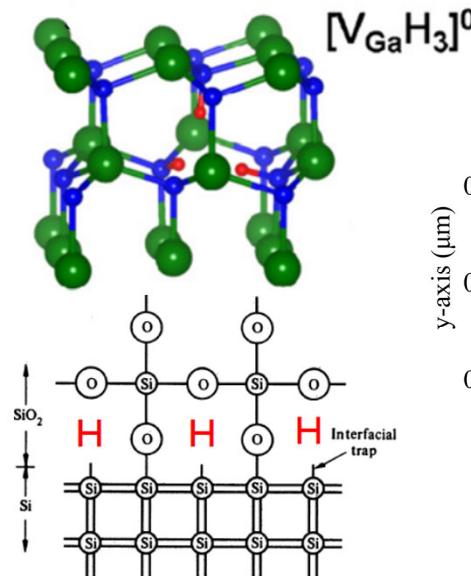
Displacement current not available (frozen field).
Need holes and self-consistency with Poisson (Ramos theorem).



4. Dehydrogenation of V_{Ga} -H₃ complexes at the GaN-AlGaN interface



- Study of the dehydrogenation of V_{Ga} -H₃ complexes at the GaN-AlGaN interface [1,2] of a p-channel HEMT. Holes are easier: higher DoS – Nichols, Pantelides (VU), and Zhang (UF)
- Monte Carlo hole energy distributions in GaN serve as input to calculate dehydrogenation rate
- ...in progress



[1] S. T. Pantelides *et al.*, Microelectron. Eng. **90**, 3 (2012)

[2] L. Nichols, unpublished and PhD Thesis (2024)

Conclusions and plans

- First principles study of electron transport in the “10-100 eV gap” (wurtzite GaN, C-diamond, β -Ga₂O₃, Si, SiC)
 - Included band structure effects up to 100 eV
 - Studied plasmon and impact ionization in this regime
 - Very short plasmon lifetime
 - Fast ($10^{-17} - 10^{-16}$ s) plasmon-induced energy losses; phonon-assisted thermalization in 1 ps or so
 - Spatial ‘spread’ of $\sim 100\text{-}200$ nm in the first ps (bad for devices?), highly anisotropic in β -Ga₂O₃
 - Average energy/pair ($\lesssim 2 - 3E_{\text{gap}}$) in agreement with experimental values
- Ready (almost) to study SEEs/SEUs and radiation-induced device degradation
 - Studied relaxation of the ‘streak’ in GaN/AlGaN HEMTs, but must implement MC holes
 - Calculation of transport characteristics of C, β -Ga₂O₃, ... (low-field mobility, velocity-field)
 - Collaborate with Vanderbilt Univ. (Fleetwood, Pantelides, Schrimpf) to account for hot-electron defect generation (e.g., H release) and for scattering with radiation-induced defects in FETs
 - Study carrier relaxation in other materials (SiO₂, AlN, AlGaN, etc.)
 - Investigate temperature effects (?)



More stuff

Overview of the problem

- Ionizing radiation in devices → high-energy charge carriers
 - Nuclear/particle physics community: Binary-collision codes [1,2]
 - Accurate down to ~ 100 eV [3]
 - Band structure effects?
 - Electronic device community: Full-band Monte Carlo [4]
 - Region below $\sim 5\text{-}10$ eV: well studied
 - Intermediate energy range: $\sim 10\text{-}100$ eV
 - Energy-loss processes: free-electrons, plasmon emission -- mostly MFP in metals [5], simplified models in semiconductors [6,7] and SiO_2 [8], no phonon losses, no time scale of the dynamics
- Close the ‘gap’ using *ab initio* methods
- Increasing interest in wide-bandgap materials
 - Focus on GaN (wurtzite), C (diamond), and $\beta\text{-Ga}_2\text{O}_3$

[1] R. A. Reed, *et al.*, IEEE Trans. Nucl. Sci. **62**, 1441 (2015).

[2] S. Agostinelli, *et al.*, Nucl. Instrum. Methods Phys. Res. A: Accel. Spectrom. Detect. Assoc. Equip. **506**, 250 (2003).

[3] C. M. Dozier and D. B. Brown, IEEE Trans. Nucl. Sci. **28**, 4137 (1981).

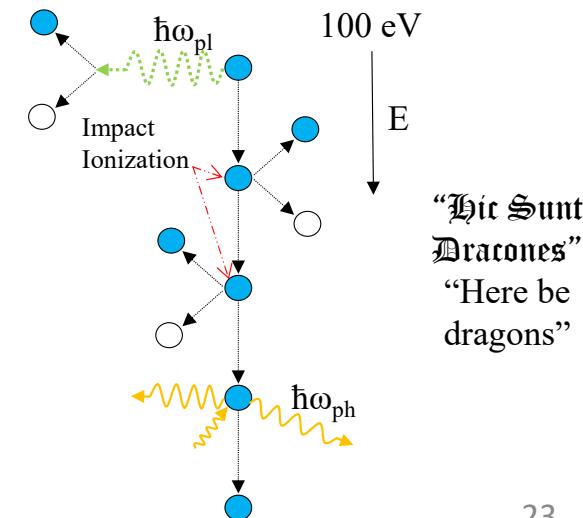
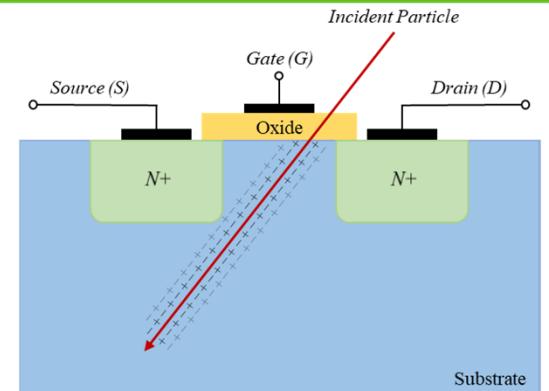
[4] H. Shichijo and K. Hess, Phys. Rev. B **23**, 4197 (1981).

[5] D. Pines, Rev. Mod. Phys. **28**, 184 (1956). J. J. Quinn and R. A. Ferrel, Phys. Rev. **112**, 812 (1958); J. J. Quinn, Phys. Rev. **126**, 1453 (1962); D. R. Penn, Phys. Rev. B **35**, 482 (1982).

[6] R. C. Alig, S. Bloom, and C. W. Struck, Phys. Rev. B **22**, 5565 (1980).

[7] A. Akkerman, J. Barak, and D. Emfietzoglou, Nucl. Inst. Meth. Phys. Res. B **227**, 319 (2005).

[8] G. A. Ausman Jr. and F. B. McLean, Appl. Phys. Lett. **26**, 173 (1975).



Scattering rates from the energy-loss function: Numerical details



- Discretize the Brillouin zone (as usual) into volume elements centered at \mathbf{k}_j with density of states $\mathcal{D}_{jn}(E)$ for band n at energy E (from the Gilat-Raubenheimer [1] or tetrahedron [2] methods); tabulate $E_n(\mathbf{k}_i)$
- Discretize the ω -axis into elements of width $\Delta\omega$ centered at ω_r and tabulate $\text{Im} \left[\frac{-1}{\varepsilon(\mathbf{q}_i, \omega_r)} \right]$
- Evaluate energy-loss rate:

$$\text{as: } \frac{1}{\tau_n(\mathbf{k})} = \frac{2\pi}{\hbar} e^2 \hbar \sum_{n'} \int \frac{d\mathbf{q}}{(2\pi)^3 q^2} \frac{1}{\varepsilon(q, \omega)} \int d\omega \text{Im} \left[\frac{-1}{\varepsilon(q, \omega)} \right] \delta[E_n(\mathbf{k}) - E_{n'}(\mathbf{k} + \mathbf{q}) + \hbar\omega],$$

$$\frac{1}{\tau_n(\mathbf{k}_i)} = 2\pi e^2 \sum_{n', \omega_r} \Delta\omega \sum_{\mathbf{k}_j} \frac{1}{|\mathbf{k}_i - \mathbf{k}_j|^2} \text{Im} \left[\frac{-1}{\varepsilon(|\mathbf{k}_i - \mathbf{k}_j|, \omega_r)} \right] \mathcal{D}_{jn'}[E_n(\mathbf{k}_i) - \hbar\omega_r].$$

The sum over \mathbf{k}_j spans only ‘energy-conserving’ elements selected using the Gilat-Raubenheimer [1] or Blöchl’s tetrahedron method [2]

- In the Monte Carlo simulations, after a collision, select a random band n' , wavevector \mathbf{k}_j , and energy-loss $\hbar\omega_r$ with probability distribution given by the ‘integrand’ of the equation above (using the ‘rejection technique’[3])
- Account for Landau damping by generating an electron-hole pair with total kinetic energy $\hbar\omega_r - E_{\text{gap}}$

[1] G. Gilat and L. J. Raubenheimer. Phys. Rev. **144**, 390 (1966).

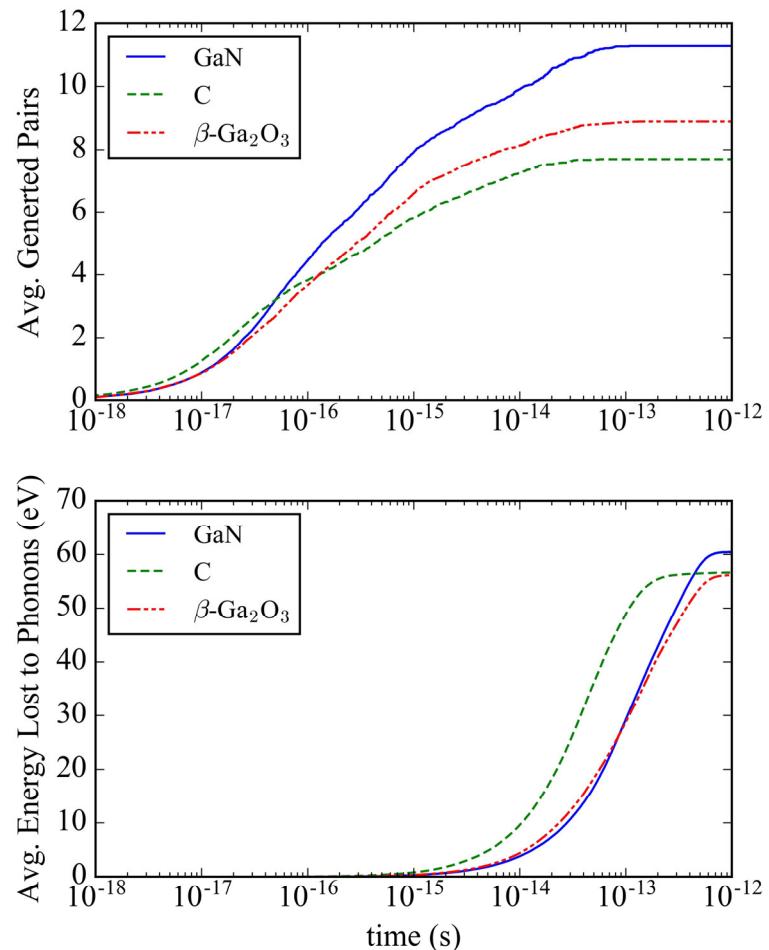
[2] P. E. Blöchl, O. Jepsen, and O. K. Andersen, Phys. Rev. B **49**, 16223 (1994).

[3] Jacoboni and L. Reggiani, Rev. Mod. Phys. **55**, 645 (1983).

Where does the energy go?

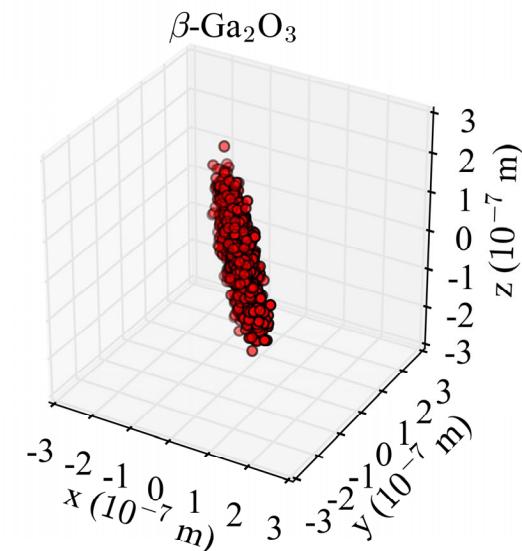
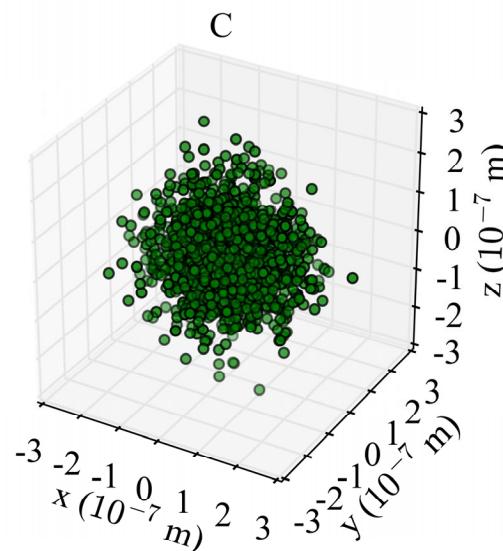
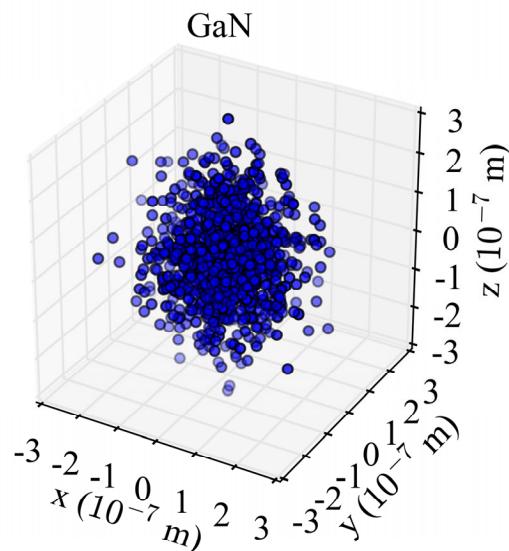


- At short times, for $t < 10^{-14}$ s, energy distributed among e-h pairs
- At $\sim 10^{-14}$ s, phonon emission increases significantly, pair generation flattens
- Somewhat more energy deposited into lattice for GaN than C and $\beta\text{-Ga}_2\text{O}_3$ (60% vs. 56-57%) .
- Fewer pairs generated in C and $\beta\text{-Ga}_2\text{O}_3$
→ larger creation energy
- Left-over energy: Recombination [1], ignored here
(small density for Auger, much longer times for SRH)
- Temperature effects
 - Ignore, for now: Assume low carrier/phonon density
 - No problems early on, may be a factor for $t > 10^{-13}$ s

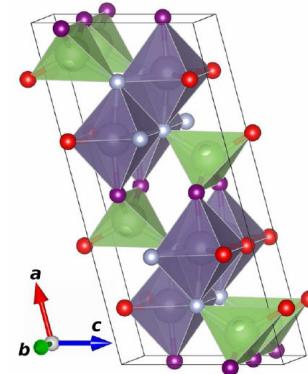


[1] S. Jursenas, *et al.*, *J. Cryst. Growth* **281**, 161 (2005).

Diffusion in real space



- After full thermalization, ~ 1 ps, electrons diffuse over ~ 100 nm
 - Approximately isotropic in C and GaN, strongly anisotropic in β -Ga₂O₃ (following long edge of unit cell)



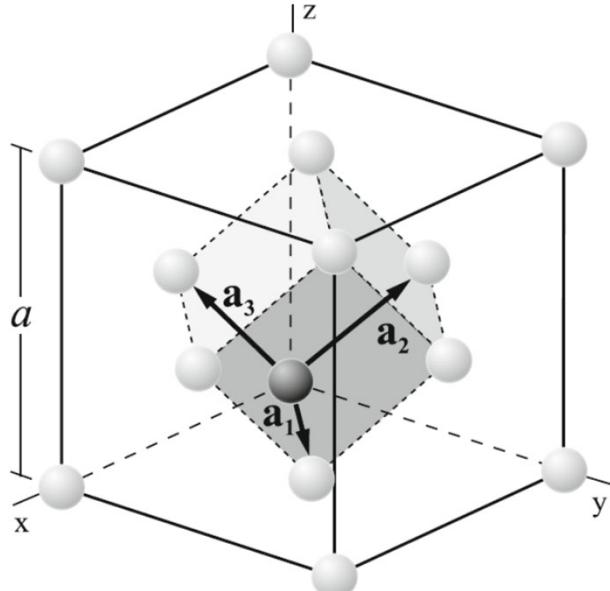
Unit cell of β -Ga₂O₃
H. Peelaers and C. Van de Walle, Phys.
Stat. Sol. B **252**, 828 (2015).

Wigner-Seitz cells:

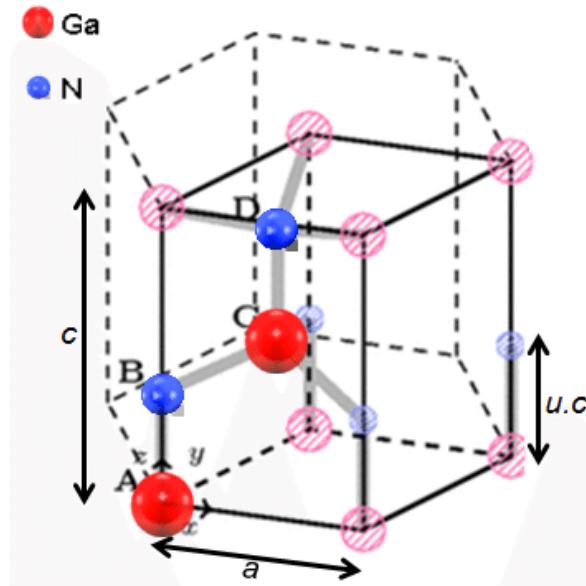
C (diamond), GaN (wurtzite), β -Ga₂O₃



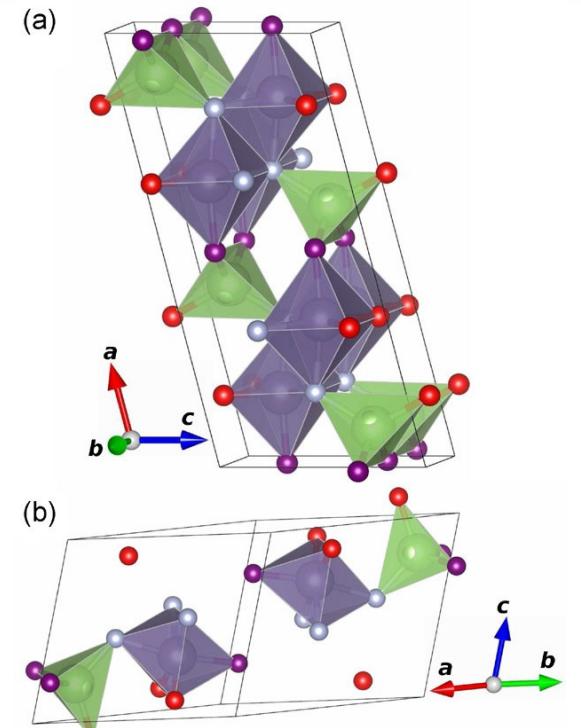
UTD



C (diamond, Fd3m)
fcc, 2 atoms/WS cell [1]



GaN (P6₃mc)
wurtzite, 4 atoms/WS cell [2]



β -Ga₂O₃ (C2/m)
monoclinic, 10 atoms/WS cell [3]

[1] M. V. Fischetti and W. V. Vandenberghe, *Advanced Physics of Electron Transport in Semiconductors and Nanostructures* (Springer, 2016)

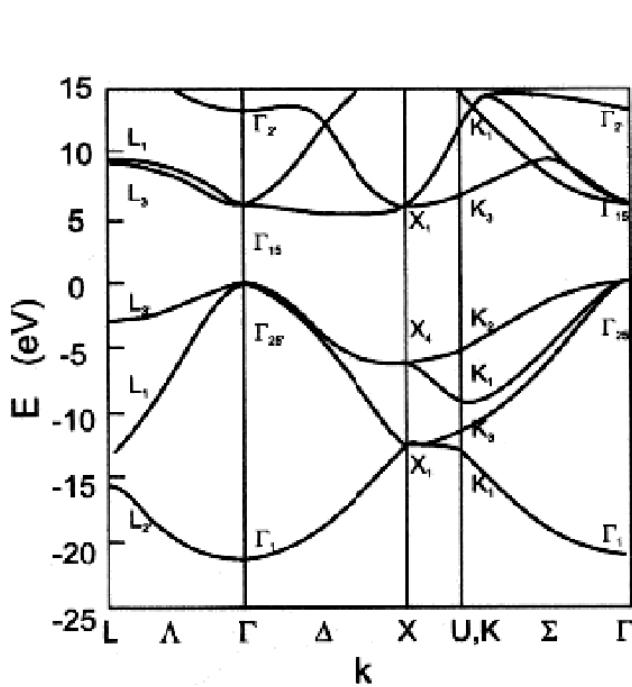
[2] D. Andiwijayakusuma *et al.*, J. Phys.: Conf. Ser. **739**, 012027 (2016).

[3] H. Peelaers and C. Van de Walle, Phys. Stat. Sol. B **252**, 828 (2015).

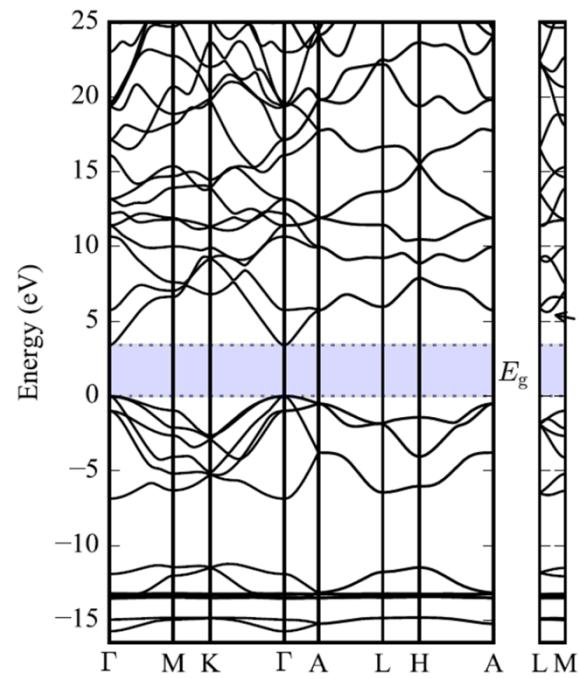
Band structure: C (diamond), GaN (wurtzite), β -Ga₂O₃



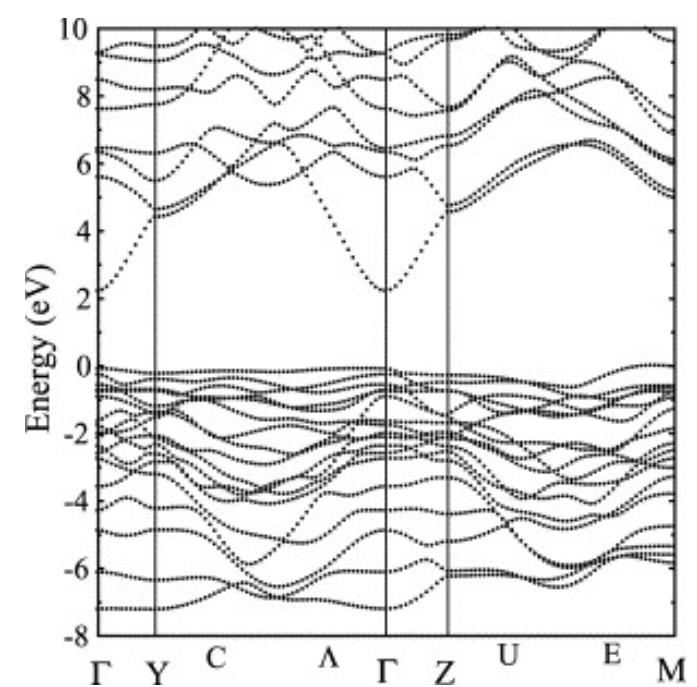
UTD



C (diamond, HSE-ONCV) [1]
PBESOL-USSP for ‘el-ph & $\varepsilon(q, \omega)$
 $E_{\text{gap}} = 5.45 \text{ eV}$



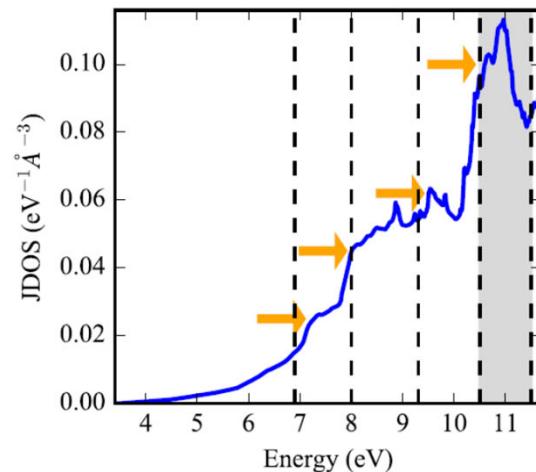
GaN (PBE-ONCV) [2]
 $E_{\text{gap}} = 1.78 \text{ eV} \rightarrow 3.4 \text{ eV}$



β -Ga₂O₃ (PBE-ONCV) [3]
PBESOL-USSP for ‘el-ph & $\varepsilon(q, \omega)$
 $E_{\text{gap}} = 2.63 \text{ eV} \rightarrow 4.8 \text{ eV}$

- [1] M. Dipalo, *Nanocrystalline diamond growth and device applications*, (Doctoral Thesis, Ulm University, 2008)
- [2] D. O. Nielsen *et al.*, Phys. Rev. B **108**, 155203 (2023).
- [3] K. Yamaguchi, Solid State Commun. **131**, 739 (2004).

Can we trust DFT up to 100 eV? The case of GaN



DFT-calculated JDOS vs. E of GaN [1]

Dashed lines: Vertical transition energies [2]

Orange arrows: JDOS peaks and

So: OK up to ~ 10 eV

More and more free-electron-like at higher energies?

	$U_{v_1-c_1}$	$M_{v_1-c_2}$	$L_{v_1-c_1}$	$K_{v_1-c_1}$	$K_{v_2-c_1}$	$A_{v_1-c_3}$	$L_{v_3-c_3}$
Our work (GGA-PBE) [1]	7.18	8.00	7.80	9.42	9.68	10.49	11.10
DFT-LDA [2]	6.87	7.65	7.64	9.57	9.68	10.53	11.05
Exp. [2]	6.9	8.0	8.0	9.3	9.3	10.5–11.5	10.5–11.5
Exp. [3]	7.1	8.1	8.1	9.2	9.2		
Exp [4]	7.0	7.9	7.9	9.0	9.0		

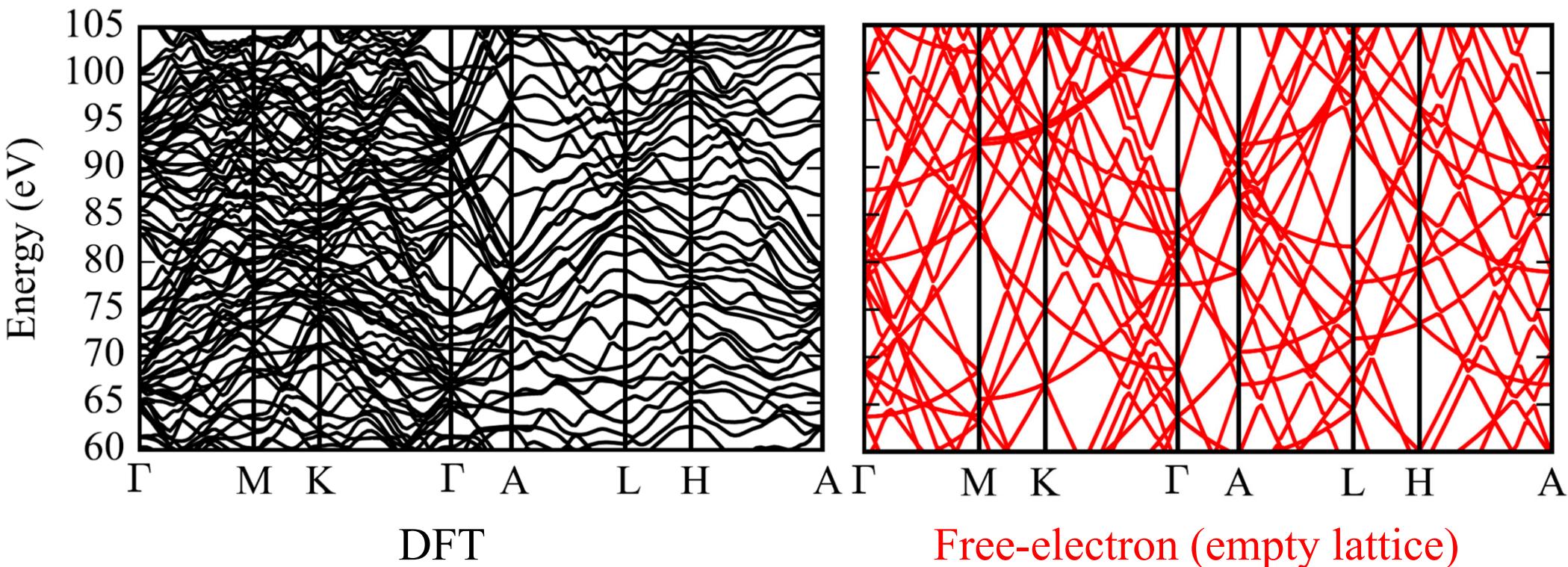
[1] D. O. Nielsen *et al.*, Phys. Rev. B **108**, 155203 (2023).

[2] W. R. L. Lambrecht *et al.*, Phys. Rev. B **51**, 13516 (1995).

[3] G. Brockt and H. Lakner, Micron **31**, 435 (2000).

[4] S. Logothetidis *et al.*, Phys. Rev. B **50**, 18017 (1994).

Free electrons at 100 eV? Hm...



Can we use 1st-order perturbation theory?



- Scattering rates as high as $5 \times 10^{16} - 10^{17}/\text{s}$ for 100 eV electrons imply a broadening $\Delta E \sim \hbar/\tau \sim 30\text{-}60 \text{ eV}$
 - Problem discussed by Quinn [1]: “[...] *the quasiparticle concept is not too bad*”
 - **Concerns even worse at lower energy (~5 eV):**
The Capasso-Hess controversy of the '80s [2,3]:
For impact ionization in GaAs, $\Delta E \gtrsim E$!
 - The ‘solution’ (*i.e.*, collisional broadening) worse than the original problem: 2nd –order corrections ‘corrected’ by higher-order terms
 - Bethe-Salpeter equation (Coulomb e-h interaction, matters in low- ϵ materials) does not help (→probably even higher rates). Need full quantum transport model (NEGF+DFT), unrealistic with up to 350 bands

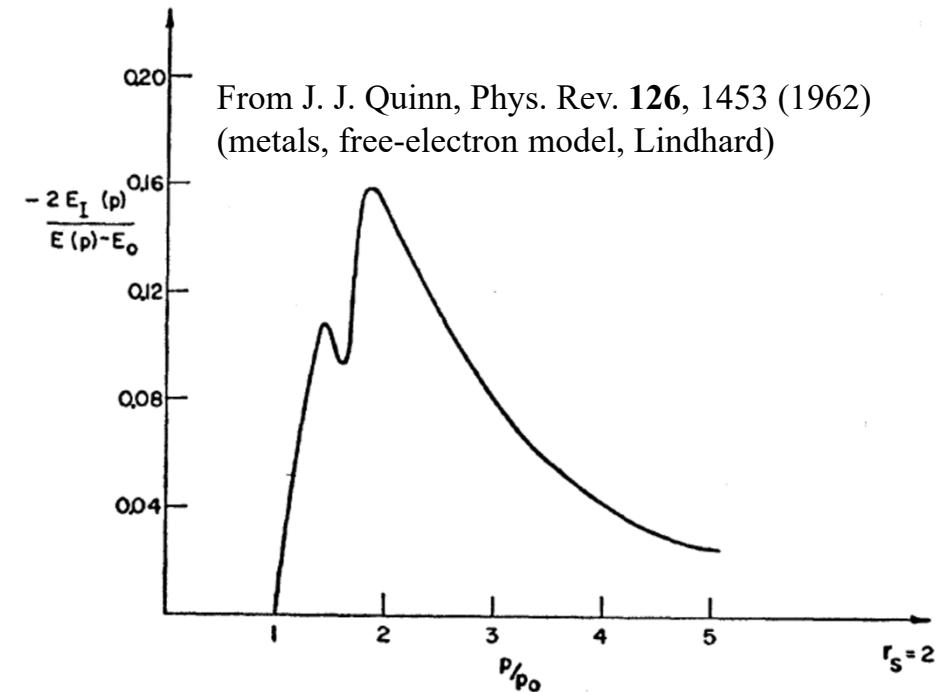


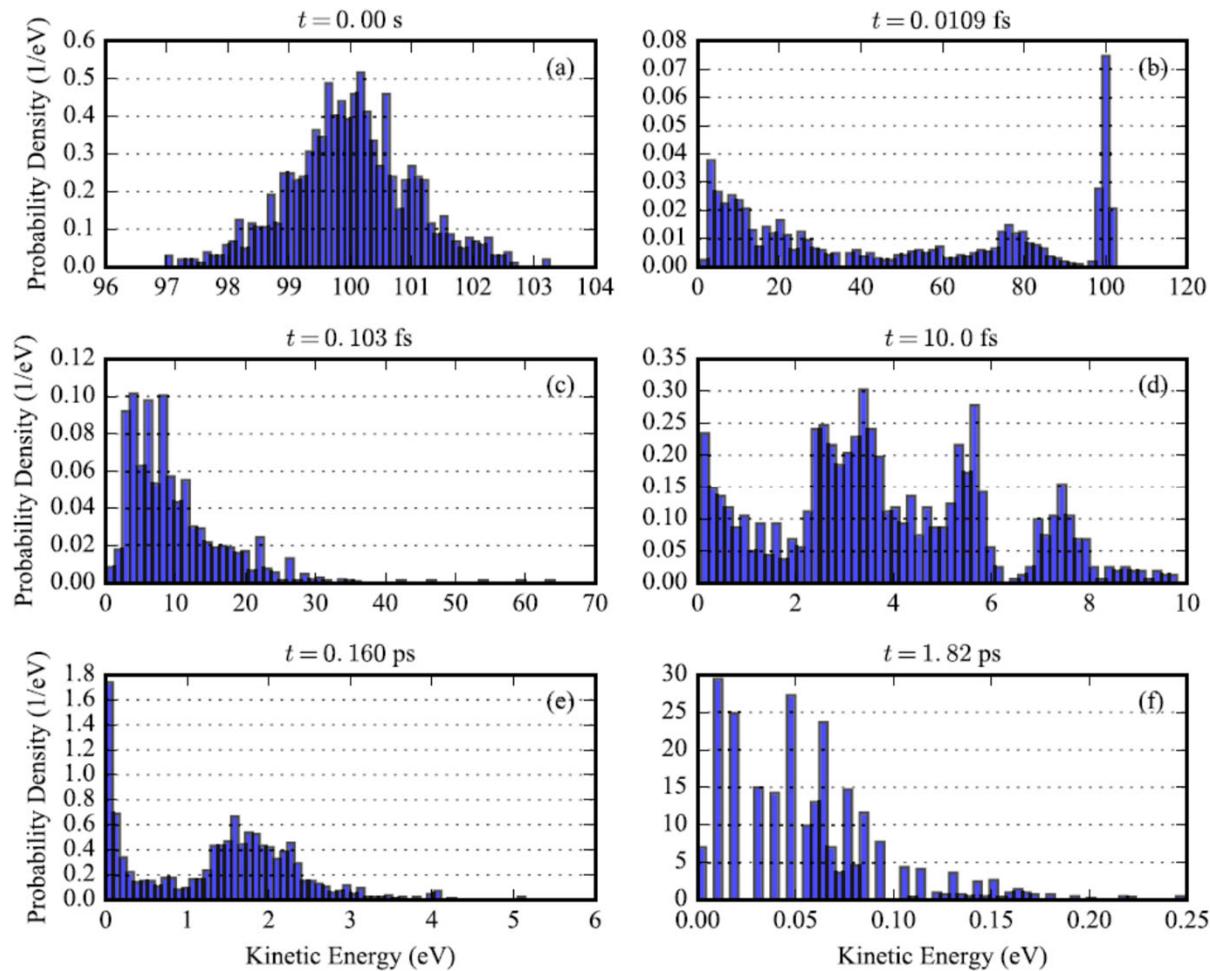
FIG. 3. The ratio of the uncertainty in the quasi-particle energy to its excitation energy as a function of p/p_0 .

[1] J. J. Quinn, Phys. Rev. **126**, 1453 (1962).

[2] F. Capasso *et al.*, J. Appl. Phys. **53**, 3324–3326 (1982).

[3] Y.-C. Chang *et al.*, Appl. Phys. Lett. **42**, 76–78 (1983).

Time evolution of the electron-energy distribution function in GaN

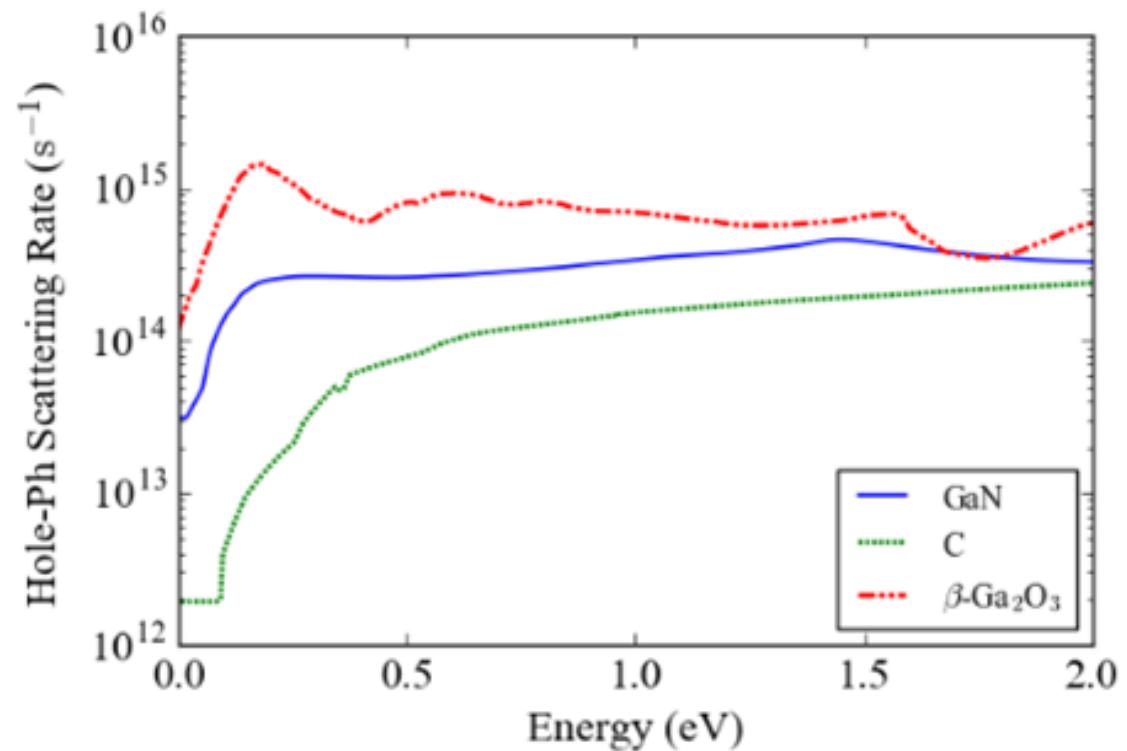


Hole-phonon scattering rates: Slow hole thermalization in C (diamond)



- Hole mobility (300K):
 - C (diamond, exp): $3,500 \text{ cm}^2/(\text{Vs})$ [1]
 - GaN (wurtzite, theory): $52 \text{ cm}^2/(\text{Vs})$ [2] (?)
(nearly intrinsic, exp): $170 \text{ cm}^2/(\text{Vs})$ [3]
 - $\beta\text{-Ga}_2\text{O}_3$ (N doped, exp): $\sim 23 \text{ cm}^2/(\text{Vs})$ [4]

Small hole mass in diamond, flat VBs in GaN
and Ga_2O_3



[1] J. Isberg *et al.*, Science **297**, 1670 (2002).

[2] S. Poncé, D. Jena, and F. Giustino, Phys. Rev. B **100**, 085204 (2019).

[3] M. Rubin *et al.*, Appl. Phys. Lett. **64**, 64 (1994).

[4] C. Ma *et al.*, J. Mater. Chem. C **10**, 6673 (2022).